

• General Description

The AGM12T02LL combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{\text{DS(ON)}}$.

This device is ideal for load switch and battery protection applications.

Features

- Advance high cell density Trench technology
- Low R_{DS(ON)} to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance
- 100% Avalanche tested
- 100% DVDS tested

Application

- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

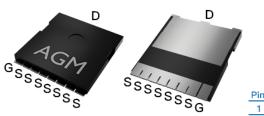
Product Summary

BVDSS	RDSON	ID
120V	2.0mΩ	230A

Bottom View

TOLL Pin Configuration

Top View



	Doodiiption
1	Gate(G)
2,3,4,5,6,7,8	Source(S)
9	Drain(D)

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
AGM12T02LL	AGM12T02LL	TOLL	330mm	25mm	2000

Table 1. Absolute Maximum Ratings (TA=25℃)

Symbol	Parameter	Value	Unit
VDS	Drain-Source Voltage (VGS=0V)	120	V
VGS	Gate-Source Voltage (VDS=0V)	±20	V
ID	Drain Current-Continuous(Tc=25℃) (Note 1)	230	А
_	Drain Current-Continuous(Tc=100℃)	165	Α
IDM (pluse)	Drain Current-Pulsed (Note 2)	920	А
PD	Maximum Power Dissipation(Tc=25℃)	380	w
	Maximum Power Dissipation(Tc=100℃)	188	w
EAS	Avalanche energy (Note 3)	1521	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 175	C

Table 2. Thermal Characteristic

Symbol	Parameter	Тур	Max	Unit
RøJC	Thermal Resistance Junction-Case ¹		0.4	°C/W



Table 3. Electrical Characteristics (TJ=25°C unless otherwise noted)

Table 3. Symbol	Electrical Characteristics (TJ=25 © unle	Conditions	Min	Тур	Max	Unit
On/Off St				71		
BVDSS	Drain-Source Breakdown Voltage	VGS=0V ID=250µA	120			V
IDSS	Zero Gate Voltage Drain Current	VDS=120V,VGS=0V			1	μA
IGSS	Gate-Body Leakage Current	VGS=±20V,VDS=0V			±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS,ID=250µA	2.0	3.0	4.0	V
gFS	Gate Threshold Voltage	VDS=5V, ID=15A		50		S
RDS(on)	Drain-Source On-State Resistance	VGS=10V, ID=20A		2.0	2.8	mΩ
Dynamic	Characteristics					
Ciss	Input Capacitance	VDS=60V,VGS=0V,		12700		pF
Coss	Output Capacitance	F=1MHZ		870		pF
Crss	Reverse Transfer Capacitance			48		pF
Rg	Gate resistance	VGS=0V, VDS=0V,f=1.0MHz				Ω
Switching	g Times					
td(on)	Turn-on Delay Time			34		nS
tr	Turn-on Rise Time	VGS=10V,VDS=60V,		27		nS
td(off)	Turn-Off Delay Time	ID=115A,RGEN=1.6Ω		78		nS
tf	Turn-Off Fall Time			30		nS
Qg	Total Gate Charge			213		nC
Qgs	Gate-Source Charge	VGS=10V, VDS=50V, ID=115A		58		nC
Qgd	Gate-Drain Charge	- ID-TION		58		nC
Source-Drain Diode Characteristics						
ISD	Source-Drain Current(Body Diode)				230	А
VSD	Forward on Voltage	VGS=0V,IS=20A			1.2	V
trr	Reverse Recovery Time	IF=20A , dl/dt=100A/μs ,		101		ns
Qrr	Reverse Recovery Charge	TJ=25℃		280		nc

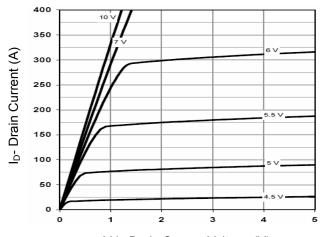
Notes 1. The maximum current rating is package limited.

Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature

Notes 3.EAS condition: TJ=25 $^{\circ}$ C,VDD=50V,Vgs=10V,ID=78A,L=0.5mH,RG=25ohm

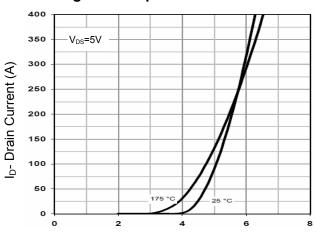


Typical Electrical and Thermal Characteristics



Vds Drain-Source Voltage (V)

Figure 1 Output Characteristics



Vgs Gate-Source Voltage (V)

Figure 2 Transfer Characteristics

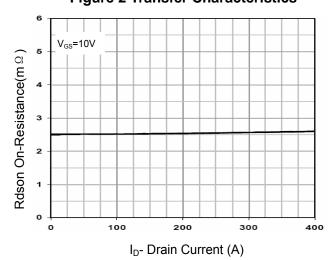
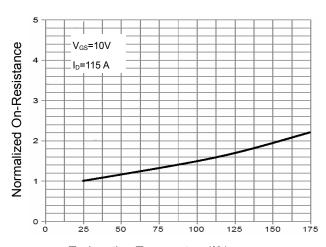
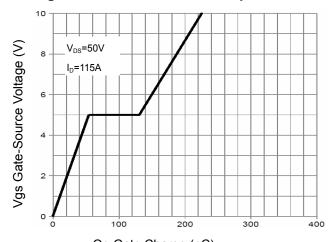


Figure 3 Rdson- Drain Current

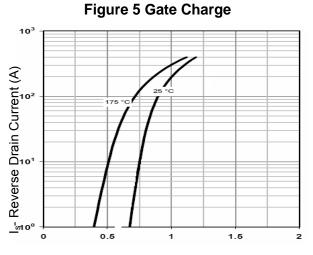


 T_J -Junction Temperature($^{\circ}$ C)

Figure 4 Rdson-Junction Temperature



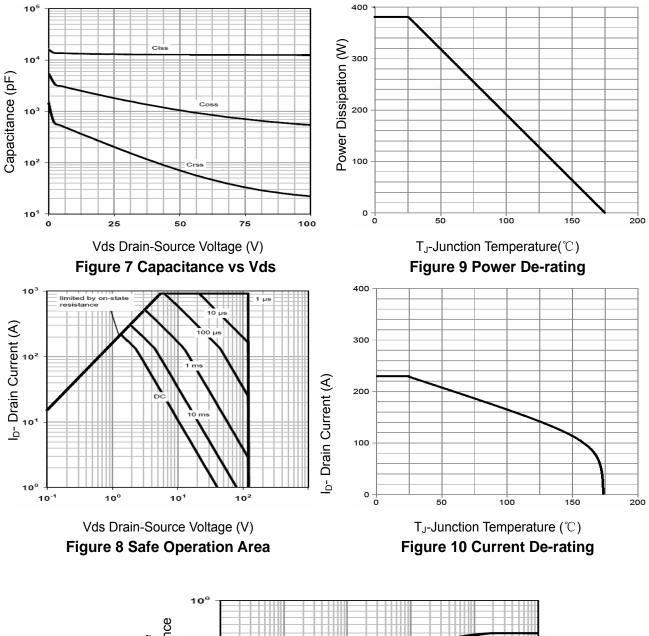
Qg Gate Charge (nC)



Vsd Source-Drain Voltage (V)

Figure 6 Source- Drain Diode Forward





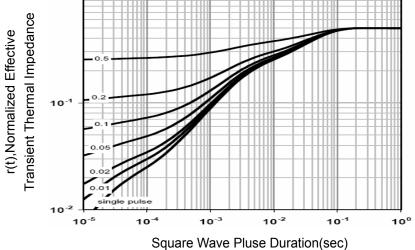
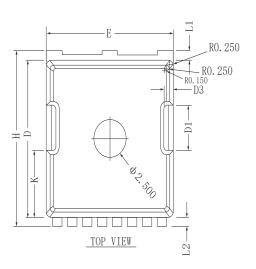
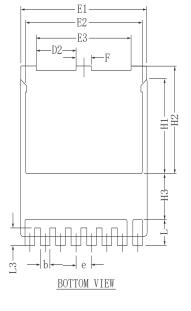


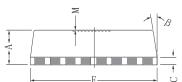
Figure 11 Normalized Maximum Transient Thermal Impedance



•Dimensions (TOLL)







Symbols	Millimeters				
3y110018	MIN.	NOM.	MAX.		
A	2.20	2.30	2.40		
b	0.65	0.75	0.85		
С		0.508 REF			
D	10.25	10.40	10.55		
D1	2.85	3.00	3. 15		
D2	2. 95	3. 10	3. 25		
D3		0.75 REF			
Е	9.75	9.90	10.05		
E1	9.65	9.80	9.95		
E2	8. 95	9.10	9. 25		
E3	7. 25	7. 25 7. 40 7. 55			
е	1.20 BSC				
F	1.05	1.20	1.35		
Н	11.55	5 11.70 11.8			
H1	6.03	6. 18	6.33		
H2	6.85	7.00	7.15		
Н3		3.00 BSC			
L	1.55	1.70	1.85		
L1	0.55	0.70	0.85		
L2	0.45	0.60	0.75		
L3	1.00	1.15	1.30		
M	0.08 REF				
β	8°	10°	12°		
K	4. 25	25 4.40 4.55			

MILLIMETER

NOM.

2.300

1.800

0.700

9.800

0.750

1.200

0.500

2.400

1.900

0.800

9.900

0.850

1.300

0.600

0.600

3.200

SYMBOL

A1

b

b1

b2 b3 MIN.

2.200

1.700

0.600

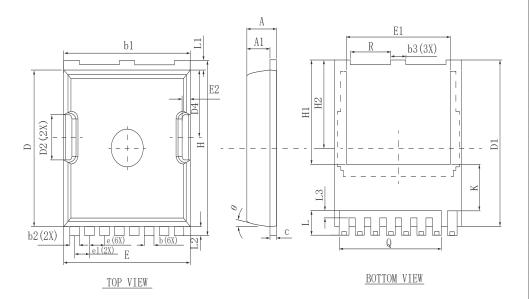
9.700

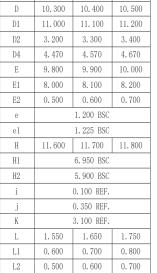
0.650

1.100

0.400

Millimeters





0.400

3.000

0.500 7.950 REF.

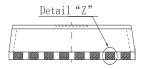
3.100 10° REF.

L3

Q

R

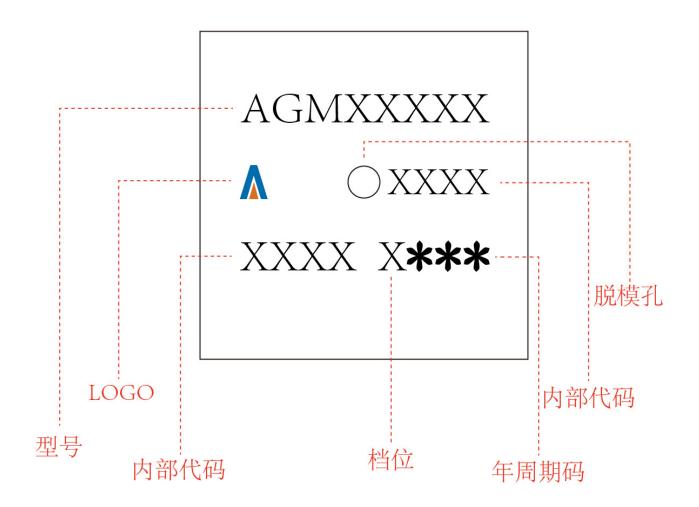
θ







TOLL
Marking Instructions:





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